

TM0085P03DF

P -Channel Enhancement Mosfet

General Description

- Low $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

Applications

- Load switch
- PWM

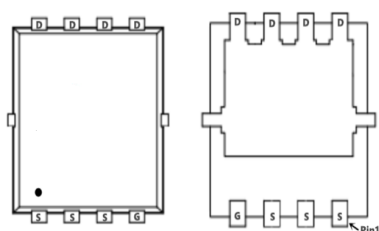
General Features

$V_{DS} = -30V$ $I_D = -55A$

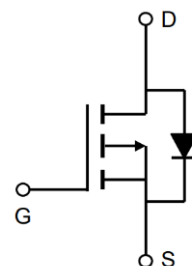
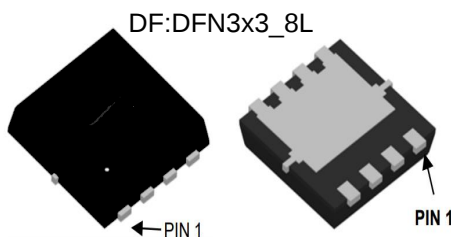
$R_{DS(ON)} = 8.5m\Omega (typ.) @ V_{GS} = -10V$

100% UIS Tested

100% R_g Tested



Marking: 55P03 OR 3419A



Absolute Maximum Ratings ($T_A = 25^\circ C$, unless otherwise noted)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		-30	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ C$	-55	A
		$T_C = 100^\circ C$	-23	A
I_{DM}	Pulsed Drain Current ^{note1}		-140	A
E_{AS}	Single Pulsed Avalanche Energy ^{note2}		78.8	mJ
P_D	Power Dissipation	$T_C = 25^\circ C$	21.5	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		5.8	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ C$

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Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D = -250μA	-30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -30V, V _{GS} = 0V,	-	-	-1	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-1.0	-1.5	-2.5	V
R _{DS(on)}	Static Drain-Source on-Resistance note3	V _{GS} =-10V, I _D =-12A	-	8.5	11	mΩ
		V _{GS} =-4.5V, I _D =-8A	-	13	18	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = -15V, V _{GS} = 0V, f = 1.0MHz	-	2800	-	pF
C _{oss}	Output Capacitance		-	346	-	pF
C _{rss}	Reverse Transfer Capacitance		-	319	-	pF
Q _g	Total Gate Charge	V _{DS} = -15V, I _D = -20A, V _{GS} = -10V	-	30	-	nC
Q _{gs}	Gate-Source Charge		-	5.3	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	7.6	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} = -15V, I _D = -20A, V _{GS} =-10V, R _{GEN} =2.5Ω	-	14	-	ns
t _r	Turn-on Rise Time		-	20	-	ns
t _{d(off)}	Turn-off Delay Time		-	95	-	ns
t _f	Turn-off Fall Time		-	65	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _s	Maximum Continuous Drain to Source Diode Forward Current		-	-	-55	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-140	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = -35A	-	-0.8	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: $T_J = 25^{\circ}\text{C}$, $V_{DD} = -20V$, $V_G = -10V$, $L = 0.5mH$, $R_G = 25\Omega$, $I_{AS} = -17A$

3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

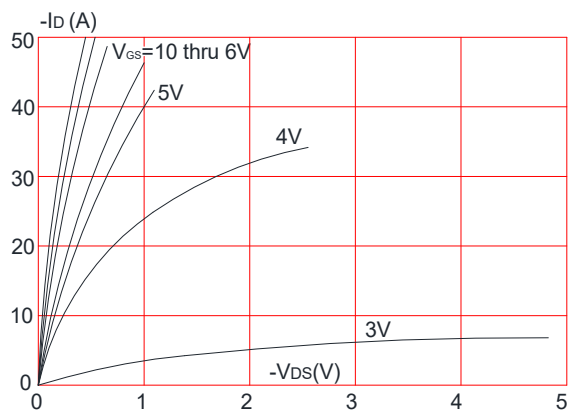


Figure 2: Typical Transfer Characteristics

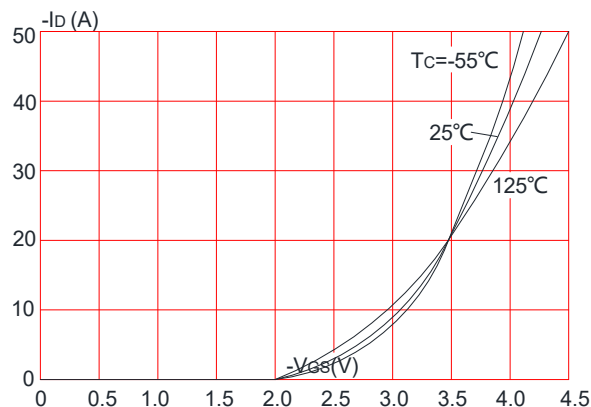


Figure 3: On-resistance vs. Drain Current

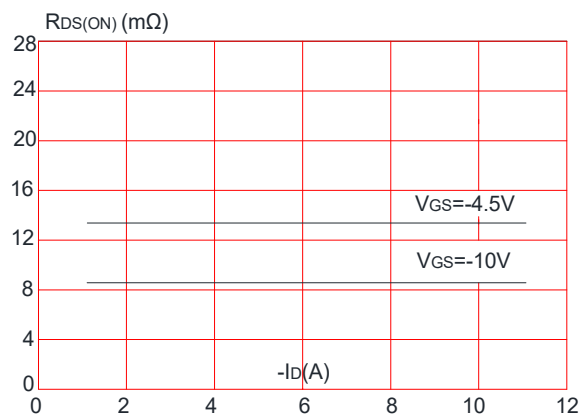


Figure 4: Body Diode Characteristics

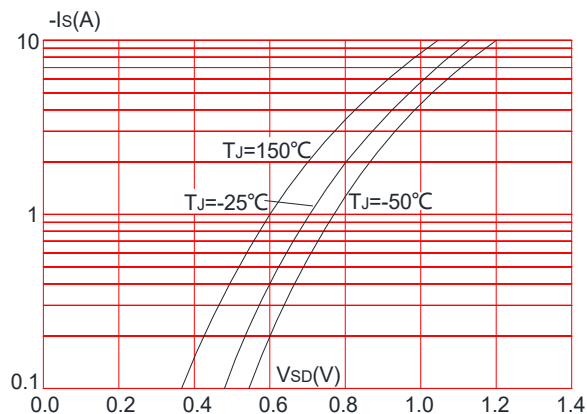


Figure 5: Gate Charge Characteristics

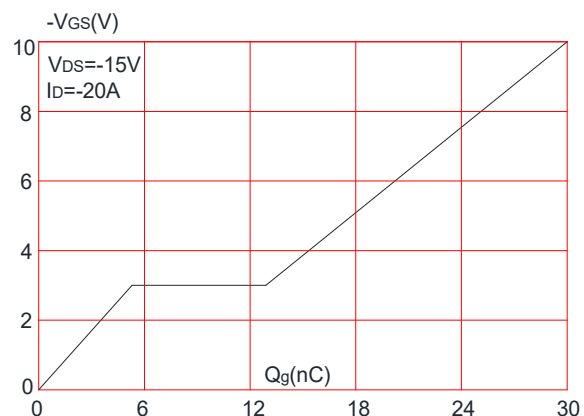
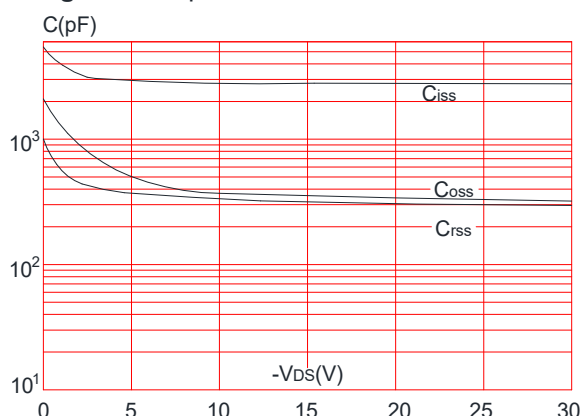


Figure 6: Capacitance Characteristics



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Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

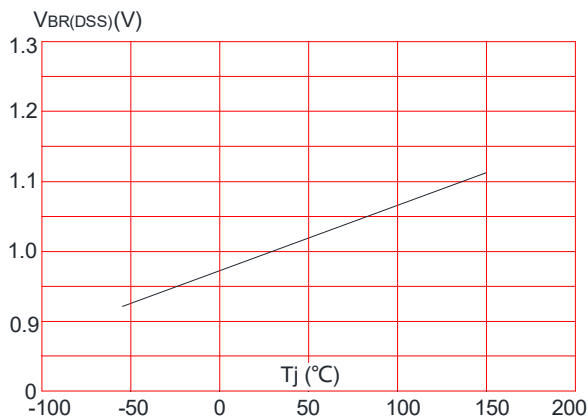


Figure 8: Normalized on Resistance vs. Junction Temperature

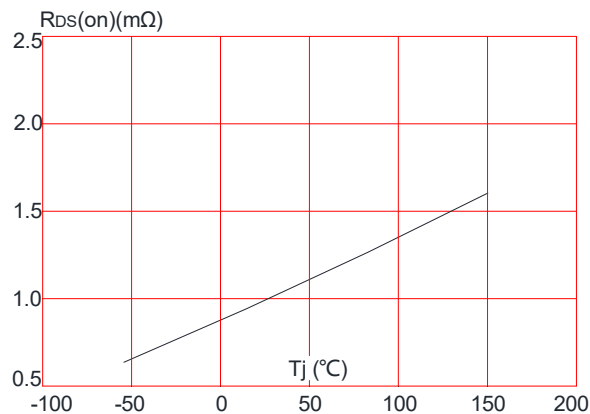


Figure 9: Maximum Safe Operating Area

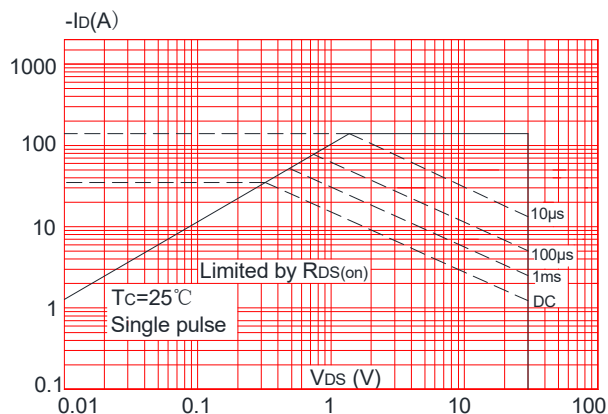


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

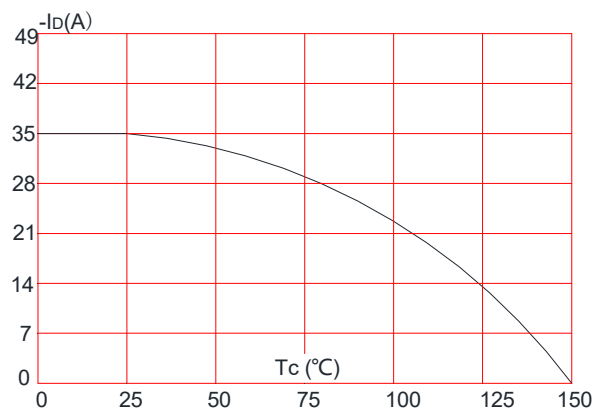
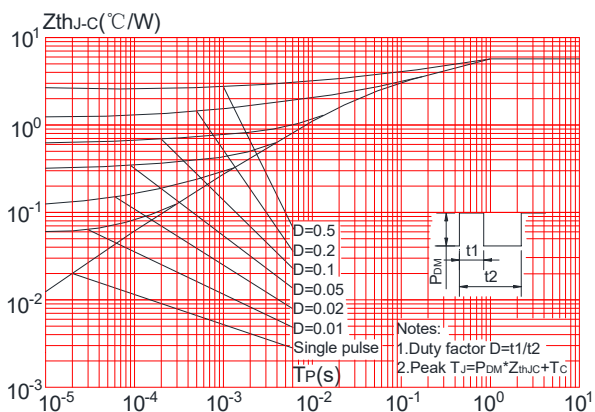
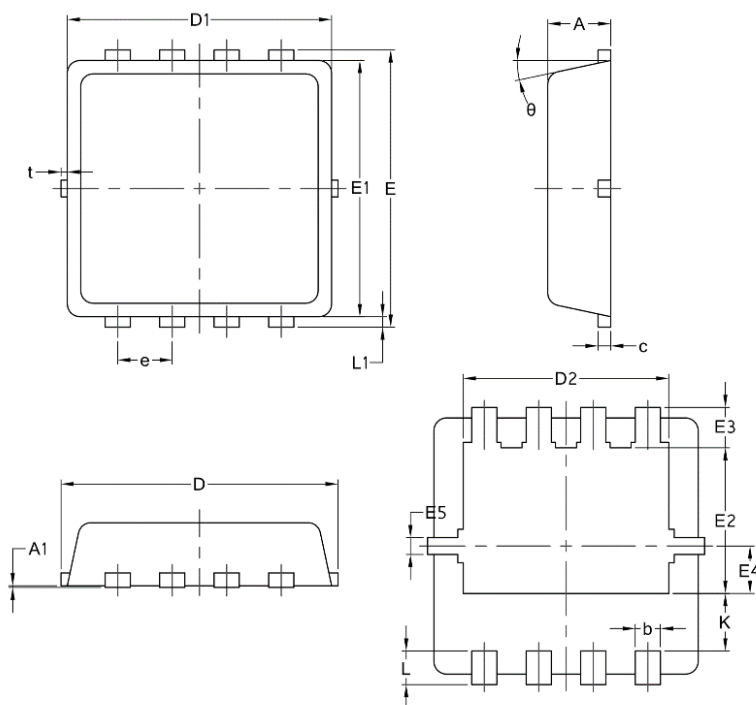


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



Package Mechanical Data:DFN3x3-8L



Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
Φ	10	12	14